

Claims

1. A carrier device (1) for a monolithic integrated circuit (7), the carrier device (1) having portions for the connection of bonding wires (5, 6) in the form of raised pedestals (2, 2') which rise above a chip connection area on the carrier device (1).
2. A carrier device (1) as claimed in claim 1, characterized in that the raised pedestals (2, 2') have sides (3) with an angle (α) greater than 45 degrees with respect to the plane of the carrier device (1).
3. A carrier device (1) as claimed in claim 1 or 2, characterized in that the raised pedestals (2, 2') each have a plane surface which is parallel to the plane of the chip connection area and comprises at least the area for the connection of a single bonding wire (5, 6).
4. A carrier device (1) as claimed in any one of claims 1 to 3, characterized in that height (h_p) of the raised pedestals (2, 2') lies in the range between 1/10 and 1.5 times the chip height.
5. A carrier device (1) as claimed in any one of claims 1 to 3, characterized in that the height (h_p) of the raised pedestals (2, 2') lies in the range from 1/5 to twice the material thickness (h) of the carrier device (1).

6. A carrier device (1) as claimed in any one of claims 1 to 5, characterized in that the raised pedestals (2, 2') each represent a local deformation of the carrier device (1) which is formed by means of a punch or a bending-off device.

7. A carrier device (1) as claimed in any one of claims 1 to 5, characterized in that the raised pedestals (2, 2') are formed by application of material to the carrier device (1).

8. A carrier device (1) as claimed in any one of claims 1 to 7, characterized in that only in the areas of the raised pedestals, a finish, particularly silver or gold, is provided for bondability.

9. A carrier device (1) as claimed in any one of claims 1 to 8, characterized in that there is at least one unbonded raised pedestal (2') on the carrier device (1).

10. A carrier device (1) as claimed in claim 9, characterized in that it comprises only unbonded raised pedestals (2'), which serve particularly as points of fixation in relation to a delamination.